

FABRICATION / ASSEMBLY NOTES:
(UNLESS OTHERWISE SPECIFIED)

1. MATERIAL: SEE BOARD LAYER STACK
2. NUMBER OF ELECTRICAL LAYERS: 4 + FRAME
3. THICKNESS: 125ML (FINISHED) + 325ML FRAME (FINISHED)
4. FINISH: IMMERSION PLATE EXPOSED AREAS AFTER APPLYING SOLDER MASK WITH ELECTROLESS NICKEL IMMERSION GOLD, AU < 0.5um
5. SOLDER MASK: LIQUID PHOTOMAGEABLE SOLDER MASK PER IPC-SM-840
COLORS SEE TABLE, 10-50um THK, BOTH SIDES, AFTER PLATING. REGISTRATION TO BE WITHN +/- 50um OF THE ASSOCIATED CIRCUIT LAYER
6. SILKSCREEN: SILKSCREEN TOP SIDE USING NONCONDUCTIVE INK COLOR BLACK
7. ALL VIA-IN-PAD STRUCTURES TO BE COMPLETELY FILLED WITH NON-CONDUCTIVE EPOXY AND PLATED OVER WITH COPPER
8. FRAME TO BE BONDED TO PCB WITH PRESSURE SENSITIVE ADHESIVE
9. ROUTE ALL CUTOUTS WITH SMALLEST MILL DIAMETER POSSIBLE
10. NO QA/QC/TEST/FAB MARKINGS OR STICKERS ANYWHERE ON THE PCB OR FRAME
11. NO CHANGES TO ANY PCB OR FRAME FEATURE WITHOUT APPROVAL FROM CUSTOMER

Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Taiyo-SM	0.60mil	3.9
	Top Plating	Nickel, Gold		
1	Lyr1		2.70mil	
	Prepreg1	370HR - 106.76% + 370HR - 106.76%	4.12mil	3.7
2	Lyr2		1.20mil	
	Core1	370HR - 4.0mils	4.00mil	4.23
3	Lyr3		1.20mil	
	Prepreg2	370HR - 106.76% + 370HR - 1080.66%	4.92mil	3.79
	Core2	370HR - 93.0mils	90.60mil	4.04
	Prepreg3	370HR - 1080.66% + 370HR - 106.76%	5.30mil	3.79
	Core3	370HR - 4.0mils	4.00mil	4.23
	Prepreg4	370HR - 106.76% + 370HR - 106.76%	4.60mil	3.7
4	Lyr4		1.80mil	
	Bottom Plating	Nickel, Gold		
	Bottom Solder	Taiyo-SM	0.60mil	3.9

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair
▽	40	0.152mm (6.00mil)	PTH	Round	Lyr1 - Lyr2
□	320	0.254mm (10.00mil)	PTH	Round	(Mixed)
○	20	0.330mm (13.00mil)	PTH	Round	(Mixed)
	380 Total				

LAYER TITLE	COLOR / EXTENSION
DRILL DRAWING	
FRAME OUTLINE	BLACK / GMD

